Amendments to the Claims

1. (CURRENTLY AMENDED) A Silicon on Insulator (SOI) device having an SOI region, a buried oxide region, and a P-Type inversion region, the P-type inversion region forming a first junction with the buried oxide layer and a second junction with the SOI layer, the buried oxide layer forming a third junction with the SOI layer, the P-type inversion region having a tongue [[303]] that extends into the third junction.

2. (CURRENTLY AMENDED) The device of claim 1 having a source and drain region and wherein the tongue [[303]] is closer to the source region than to the drain region.

3. (PREVIOUSLY PRESENTED) The device of claim 2 further comprising a handler wafer biased at a voltage greater than said source voltage.

4. (PREVIOUSLY PRESENTED) The device a claim 3 having a gate region, and wherein said gate and said source regions are biased at 50 or more volts less than said handler wafer, and wherein said drain voltage is biased at 50 or more volts greater than said handler wafer.

5. (PREVIOUSLY PRESENTED) The device of claim 2 wherein said tongue is comprised of Boron atoms.

6. (ORIGINAL) The device of claim 5 wherein said boron atoms are implanted at a concentration of 3e12 atoms/cm^2.

7. (PREVIOUSLY PRESENTED) A silicon on insulator (SOI) device having a an SOI layer, an adjacent buried oxide layer, and an inversion layer, the inversion layer having an extension that extends between the buried oxide layer and the SOI layer.

8. (ORIGINAL) The device of claim 7 wherein the extension is less than 1 micron in thickness.

9. (ORIGINAL) The device of claim 7 wherein the extension comprises P-type doping.

10. (ORIGINAL) The device of claim 9 wherein the extension comprises boron atoms.

11. (PREVIOUSLY PRESENTED) The device of claim 9 further comprising source, drain, gate, and a wafer handler regions, and a voltage source connected to bias said wafer handler at a voltage less than that at which said drain is biased and greater than that at which said source is biased.

12. (ORIGINAL) The device of claim 11 wherein said drain is biased at a voltage of approximately 200 volts higher than said source.

13. (PREVIOUSLY PRESENTED) An SOI device comprising an N-Well region, a buried oxide region, and a P-inversion region, the P-inversion region eing extended into a junction between said N-Well region and said buried oxide region, said SOI device having a substrate region biased at a voltage between a bias voltage applied to a source of said device and a bias voltage applied to a drain of said device.

14. (ORIGINAL) The SOI device of claim 13 wherein a portion of the P-inversion region that extends into the junction is doped with charge in an amount such that it is depleted by the bias applied to the substrate layer.

15. (PREVIOUSLY PRESENTED) A Silicon on Insulator (SOI) device having an SOI region, a buried oxide region, and a P-Type inversion region, the P-type inversion region forming a first junction with the buried oxide layer and a second junction with the SOI layer, the buried oxide layer forming a third junction with the SOI layer, the P-type inversion region having a tongue that extends into the third junction;

the SOI device further having a source and drain region and wherein the tongue is closer to the source region than to the drain region.

16. (PREVIOUSLY PRESENTED) The device of claim 15 further comprising a handler wafer biased at a voltage greater than said source voltage.

17. (PREVIOUSLY PRESENTED) The device a claim 16 having a gate region, and wherein said gate and said source regions are biased at 50 or more volts less than said handler wafer, and wherein said drain voltage is biased at 50 or more volts greater than said handler wafer.

18. (PREVIOUSLY PRESENTED) The device of claim 15 wherein said tongue is comprised of Boron atoms.

19. (PREVIOUSLY PRESENTED) The device of claim 18 wherein said boron atoms are implanted at a concentration of 3e12 atoms/cm^2.